

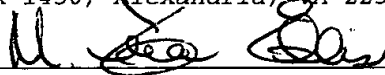


AF/2826

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Signature

Appl No. : 09/383,150  
Applicant : Rong-Fuh Shyu  
Filed : August 25, 1999  
Title : LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE,  
SEMICONDUCTOR CHIP PACKAGE INCORPORATING MULTIPLE  
INTEGRATED CIRCUIT CHIPS, AND METHOD OF FABRICATING  
A SEMICONDUCTOR CHIP...  
TC/A.U. : 2826  
Examiner : Fetsum Abraham  
Docket No. : 35761/DBP/S295  
Customer No. : 23363

LETTER

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Post Office Box 7068  
Pasadena, CA 91109-7068  
December 6, 2003  
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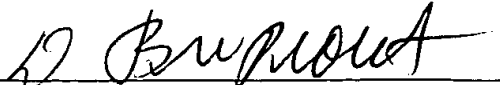
Commissioner:

The Final Rejection dated November 28, 2003 regarding the above-identified application applies only to claims 1-6, which were canceled in response to the June 23, 2003 official Office action. Therefore, the Office action does not address the claims now in this case.

Accordingly, it is requested that the November 28, 2003 Final Rejection be withdrawn and that a new Office action be issued properly addressing claims 9-12, the only claims now in this application.

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By   
D. Bruce Prout  
Reg. No. 20,958  
626/795-9900

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